



**Advanced Power  
Electronics Corp.**

**AP6800GEO**

**Pb Free Plating Product**

*N-CHANNEL ENHANCEMENT MODE*

*POWER MOSFET*

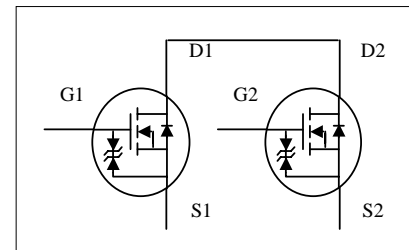
- ▼ Low on-resistance
- ▼ Capable of 2.5V gate drive
- ▼ Optimal DC/DC battery application
- ▼ RoHS compliant



$BV_{DSS}$	20V
$R_{DS(ON)}$	20m $\Omega$
$I_D$	6

## Description

The Advanced Power MOSFETs from APEC provide the designer with the best combination of fast switching, ruggedized device design, ultra low on-resistance and cost-effectiveness.



## Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	20	V
$V_{GS}$	Gate-Source Voltage	$\pm 10$	V
$I_D @ T_A = 25^\circ C$	Drain Current <sup>3</sup> , $V_{GS} @ 4.5V$	6.0	A
$I_D @ T_A = 70^\circ C$	Drain Current <sup>3</sup> , $V_{GS} @ 4.5V$	4.7	A
$I_{DM}$	Pulsed Drain Current <sup>1</sup>	30	A
$P_D @ T_A = 25^\circ C$	Total Power Dissipation	1	W
	Linear Derating Factor	0.008	W/ $^\circ C$
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ C$

## Thermal Data

Symbol	Parameter	Value	Unit
$R_{thj-a}$	Thermal Resistance Junction-ambient <sup>3</sup>	Max. 125	$^\circ C/W$



**Electrical Characteristics @T<sub>j</sub>=25°C(unless otherwise specified)**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	20	-	-	V
ΔBV <sub>DSS</sub> /ΔT <sub>j</sub>	Breakdown Voltage Temperature Coefficient	Reference to 25°C, I <sub>D</sub> =1mA	-	0.02	-	V/°C
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =4.5V, I <sub>D</sub> =6A	-	-	20	mΩ
		V <sub>GS</sub> =4V, I <sub>D</sub> =4A	-	-	21	mΩ
		V <sub>GS</sub> =2.5V, I <sub>D</sub> =2A	-	-	25	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250uA	0.5	-	1.2	V
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =10V, I <sub>D</sub> =6A	-	6	-	S
I <sub>DSS</sub>	Drain-Source Leakage Current (T <sub>j</sub> =25°C)	V <sub>DS</sub> =20V, V <sub>GS</sub> =0V	-	-	1	uA
	Drain-Source Leakage Current (T <sub>j</sub> =70°C)	V <sub>DS</sub> =16V, V <sub>GS</sub> =0V	-	-	25	uA
I <sub>GSS</sub>	Gate-Source Leakage	V <sub>GS</sub> =±10V	-	-	±30	uA
Q <sub>g</sub>	Total Gate Charge <sup>2</sup>	I <sub>D</sub> =6A	-	23.4	37	nC
Q <sub>gs</sub>	Gate-Source Charge	V <sub>DS</sub> =15V	-	2.5	-	nC
Q <sub>gd</sub>	Gate-Drain ("Miller") Charge	V <sub>GS</sub> =4.5V	-	11.1	-	nC
t <sub>d(on)</sub>	Turn-on Delay Time <sup>2</sup>	V <sub>DS</sub> =10V	-	8.2	-	ns
t <sub>r</sub>	Rise Time	I <sub>D</sub> =1A	-	18.4	-	ns
t <sub>d(off)</sub>	Turn-off Delay Time	R <sub>G</sub> =3.3Ω, V <sub>GS</sub> =5V	-	19.6	-	ns
t <sub>f</sub>	Fall Time	R <sub>D</sub> =10Ω	-	58	-	ns
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V	-	580	930	pF
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> =20V	-	315	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	f=1.0MHz	-	165	-	pF
R <sub>g</sub>	Gate Resistance	f=1.0MHz	-	2	3	Ω

**Source-Drain Diode**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V <sub>SD</sub>	Forward On Voltage <sup>2</sup>	I <sub>S</sub> =0.84A, V <sub>GS</sub> =0V	-	-	1.2	V
t <sub>rr</sub>	Reverse Recovery Time <sup>2</sup>	I <sub>S</sub> =6A, V <sub>GS</sub> =0V,	-	40	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge	dI/dt=100A/μs	-	39	-	nC

**Notes:**

- 1.Pulse width limited by Max. junction temperature.
- 2.Pulse width ≤300us , duty cycle ≤2%.
- 3.Surface mounted on 1 in<sup>2</sup> copper pad of FR4 board ; 208°C/W when mounted on Min. copper pad.

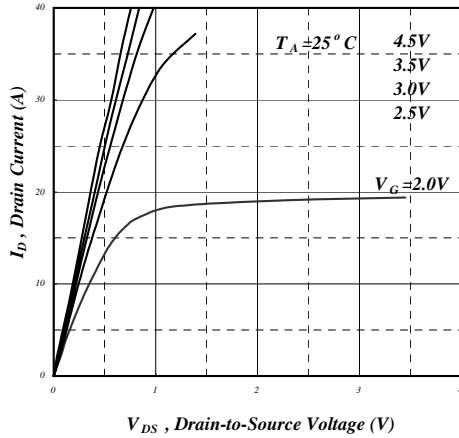


Fig 1. Typical Output Characteristics

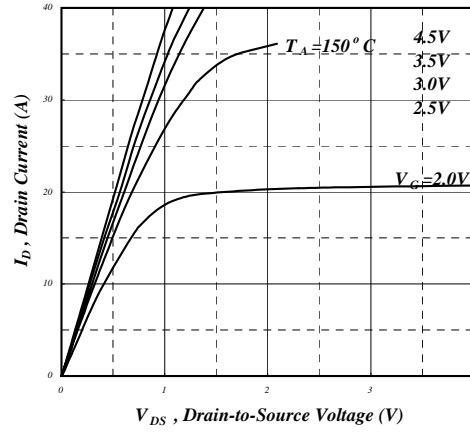


Fig 2. Typical Output Characteristics

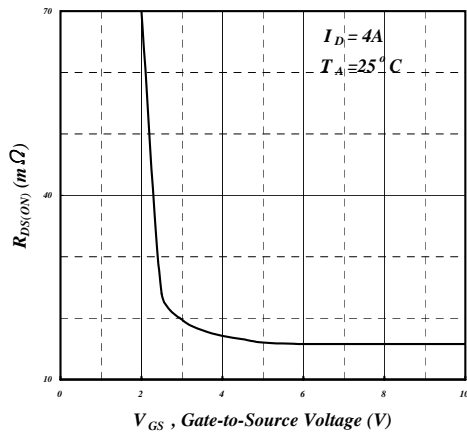


Fig 3. On-Resistance v.s. Gate Voltage

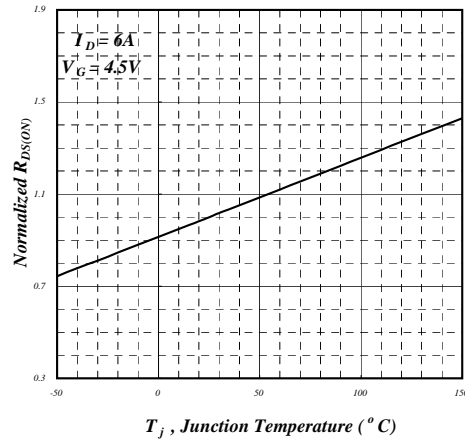


Fig 4. Normalized On-Resistance

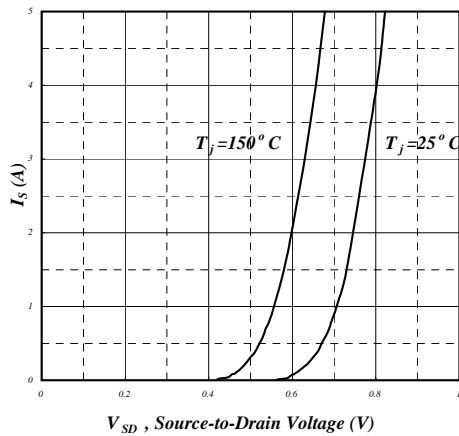


Fig 5. Forward Characteristic of Reverse Diode

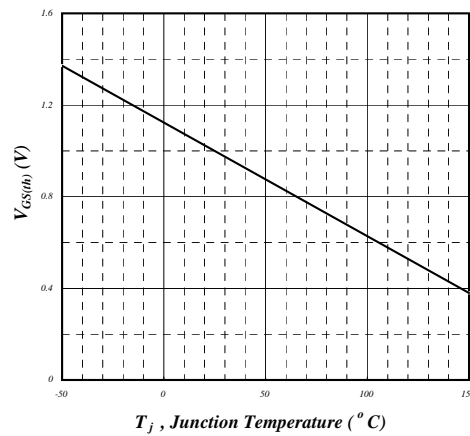


Fig 6. Gate Threshold Voltage v.s. Junction Temperature

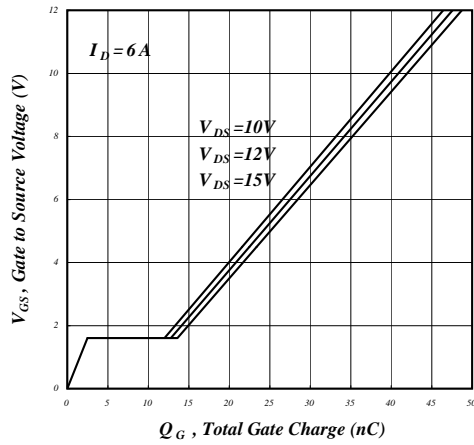


Fig 7. Gate Charge Characteristics

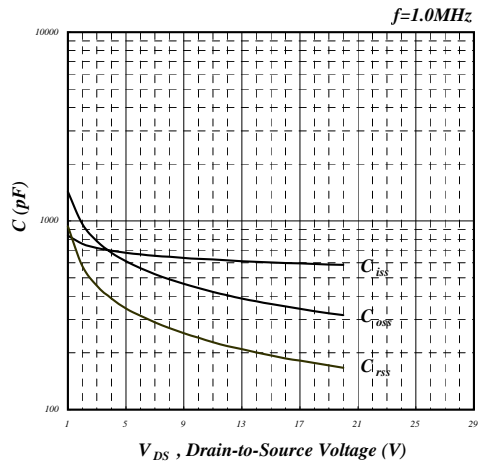


Fig 8. Typical Capacitance Characteristics

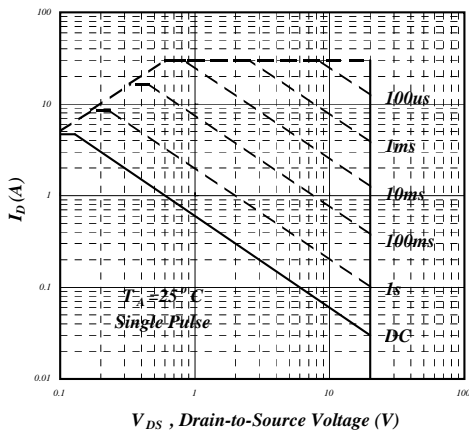


Fig 9. Maximum Safe Operating Area

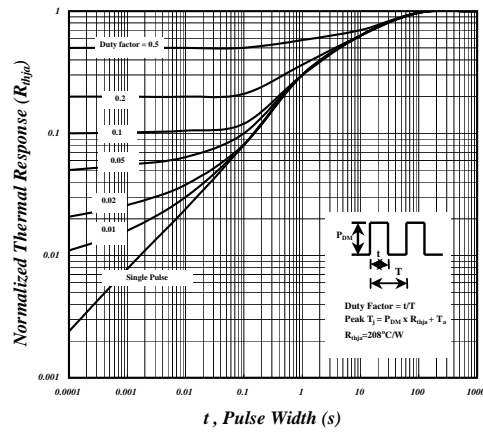


Fig 10. Effective Transient Thermal Impedance

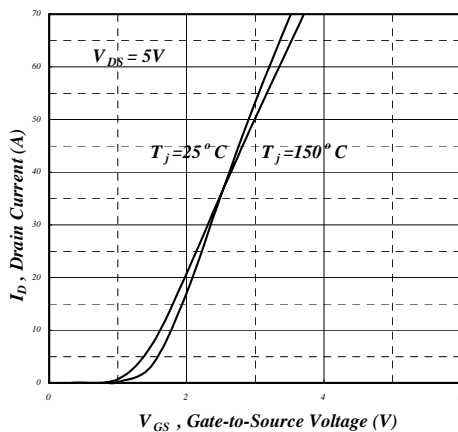


Fig 11. Transfer Characteristics

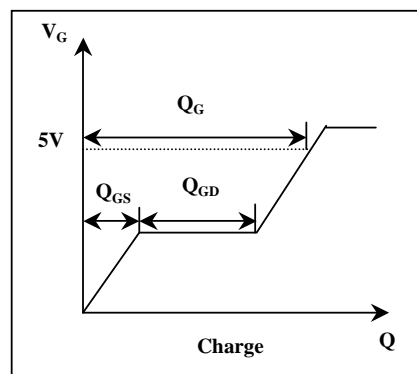


Fig 12. Gate Charge Waveform